# Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**

<table>
<thead>
<tr>
<th>Name / Model #1</th>
<th>Name / Model #2</th>
<th>Name / Model #3</th>
<th>Name / Model #4</th>
<th>Name / Model #5</th>
</tr>
</thead>
<tbody>
<tr>
<td>HP EliteBook 8530p</td>
<td></td>
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</tbody>
</table>

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Main Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Main Battery, RTC Battery</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries YES</td>
<td>1</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD unit</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>No</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. No</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>No</td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing refractory ceramic fibers | No | 0
Components, parts and materials containing radioactive substances | No | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>T8 Torx</td>
<td>T8</td>
</tr>
<tr>
<td>Cross</td>
<td>#1</td>
</tr>
<tr>
<td>Slot</td>
<td>2.5*50</td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release the main battery
2. Unscrew 6 screws on the bottom door, unscrew 2 screws for HDD cable, take out the HDD.
3. Unscrew 3 screws, take out the keyboard, unscrew 9 screws, take out the keyboard deck assy, use slot and Cross to separate Middle Cover from plastic plate.
4. Unscrew 4 screws for hinge, 2 screws for cables, take out the LCD assy.
5. Unscrew 1 screw for MB, take out the MB.
6. Unscrew 2 screws for front bezel assy, take out the front bezel assy, use slot and Cross to separate keyboard deck from plastic plate.
7. Unscrew 13 screws for LCD module, take out the LCD module.
8. Unscrew 6 screws for center hinge, take out the center hinge

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
VOX disassemble report

Michelle Ling / Mark Gao

080708
1. Disassemble the Keyboard

1. Push the battery latch for take off the battery.
2. Loosen 2 screws (M2.5X10.3)
3. Loosen the 4 latches from the KB
4. Take off the K/B and pull out the harnesses.
2. Disassemble the Middle Cover

1. Strip down 3 Middle Cover screws (M2L2.5)
2. Turn to positive and pull open the Middle Cover from top to bottom, use the slot and cross to separate Middle Cover from plastic plate.
3. Pull out the harness for take off K/B.
3. Disassemble the LCD Module

1. Remove the rubbers and strip down screws in bottom & rear of the hinges. (2 M2.5X6 T8 and 1 M2.5X4)

2. Strip down 2 screws in bottom of the hinges. (2 M2.5X6 T8)

3. Strip down the DIMM Door screws to disassemble the Door.

4. Turn to positive, strip down 2 screws and pull out all the cables then lifts the LCD Module off
4.1 Disassemble the Upper Case

1. Strip down the screws from the HDD Door
2. Strip down the screw from the HDD module and take off the HDD.
3. Strip down 2 screws (M2X2.5).
4.2 Disassemble the Upper Case

1. Strip down the ODD screw and take off the ODD Module. (Remark 1-1)
2. Strip down 2 screws (M2X2.5)
3. Strip down 2 hexagonal bolts from VGA ( #4-40 L=7.5)

Remark 1-1
Use Slotted Screwdriver to push ODD out
4.3 Disassemble the Upper Case

1. Remove the rubbers and then strip down 8 screws from the Lower Case (M2.5X6 T8)
4.4 Disassemble the Upper Case

1. Strip down 4 screws from the Upper Case (M2.5X6 T8).
2. Pull out the FFC.
3. Take off the U-Case from top to bottom.
5. Disassemble the Audio Board

1. Strip down 1 screw from the Audio Board (M2.5X6 T8).
2. Pull out the Audio cable and lift up the board from left to right for take off.
6. Disassemble the Speaker

1. Strip down 2 screws from the Speaker (M2.5X6 T8).
2. Take off the Speaker.
3. Pull out the B/T cable.
7. Disassemble the Thermal

1. Strip down 2 screws from the Fan. (M2.5X6 T8)
2. Take off the Fan.
3. Strip down 8 screws from the Heat Sink as sequence of the picture.
4. Take off the Heat Sink module.
8. Disassemble the Graphic Board

1. Strip down 2 screws from the Graphic Board (M2L4).
2. Take off the Graphic Board
9. Disassemble the WLAN Card

1. Strip down 2 screws from the WLAN card (M2.5X3 H4.7)
2. Take off the WLAN Card.
10. Disassemble the MDC

1. Strip down 2 screws from the MDC (M2XL3 H2.1)
2. Release the cable and take off the board
11. Disassemble the MB

1. Strip down 1 screw from the MB as the picture means. (M2X2.5)
2. Take out the MB from the right side.
11. Disassemble the MB

1. Use the slot and cross to separate Middle keyboard deck from plastic plate.
12.1 Disassemble the LCD

1. Remove the rubber and strip down 6 screws from the Bezel(M2.5X6).
2. Take off the Bezel.
12.2 Disassemble the LCD

1. Strip down 2 screws from the Inverter (M2.5X4)
2. Release all the cable and take the Inverter out.
12.3 Disassemble the LCD

1. Strip down 4 screws from the L-side & R-side Hinges (M2.5X4)
2. Take the Hinges out.
3. Take off the LCD Module.
12.4 Disassemble the LCD

1. Strip down 4 screws from the LCD Bracket (M2XL2.5)
13. Disassemble the HDD and ODD

1. Strip down 2 screws from the ODD Bracket (M2L3)
2. Strip down 4 screws from the HDD Bracket (M3XL4)
Thank you.